

33rd ASEMEP NATIONAL TECHNICAL SYMPOSIUM (ANTS)

"AI Horizons: Uniting Creativity and Technology for Tomorrow's Innovation"

July 26, 2024 | SMX Convention Center in Pasay City, Metro Manila

Morning Breakout Sessions

Category	Assembly & Support	Quality & Product	Test & FA/REL
Meeting Room	Track 3 (2F – MR 4)	Track 4 (2F – MR 5)	Track 5 (2F – MR 6)
Moderators & Judges	Dr. Daniel San Luis, Erwin De Guzman, Dr. Celso Co, Romulo Castillo, Jr., Aileen Jara, Sandra Chu, Chito Del Mundo & Evelyn Raguindin	James Baello, Vio Aguinaldo, Ronald Hilaria, Ruth Jacob, Rico Delmoro, Jim Apolinar Jr., Laura Clemente & Ridor Dacasin	Olsen Bandahala, Dr. Harvey Arellano, Dr. John Herber, Edgar M. Santos, Chris Elipse, Dr. Manolo Mena, Ferdinand Abitan & Rady Angeles
8:00 - 8:20 AM	[17] 3D Solid Modeling the Effective Way of Extracting Weight of Products Sub-part Materials	[13] Challenge to Error Proofing Automated Inspection Solutions to Embedded Cosmetic Defects on Optical Diffuser Wafers Using High-Resolution Chroma Equipment	[9] Using "Setup Parametric" to Identify and Resolve "Bad Sites" on Multisite Setup
	Ampleon Philippines, Inc.	STMicroelectronics, Inc.	onsemi - Carmona
	Assembly	Quality	Test
	Gerardo A. Alvano	Jhanet R. Florendo	Obrien Requina
	Zorayda S. Labausa	Carla P. Marqueses	Emmanuel Mandac
Derrick Maravilla	Kristian Paul P. Gamboa	N/A	
8:20 - 8:40 AM	[18] Intelligent Video Analytics for Improving Man- To-Machine-Ratio (MMR) in an Assembly Line	[14] Failure Analysis of Pick-And-Place's Brake Problem Through Multifactorial Experiments	[10] Elevating Efficiency: Kakarot Super Gui's Journey Towards Enhanced Productivity
	Western Digital Philippines	P. IMES Corp.	Texas Instruments Philippines, Inc. - Clark
	Assembly	Quality	Test
	Sabari Vishnu Jayanthan Jaikrishnan	Jermie A. De Mesa	Bonnierick J. Mendoza
	Janoah De Los Santos	Leonardo Z. Sarmiento	Jeric C. Del Rosario
N/A	N/A	N/A	

8:40 - 9:00 AM	[19] Process Simplification Through Elimination of Pre-Cut, Overlay and De-Tape Process for MemS Instrip Packages	[15] Reduction of Over Rejection at Marking, Orientation, and Package (MOP) Vision Inspection of Device X	[11] Tester Anomaly Detection with Machine Learning Model Prediction
	STMicroelectronics, Inc.	onsemi - Tarlac	Western Digital Philippines
	Assembly	Quality	Test
	Eric Espino	Einna Liz L. Tadeja	Melody Cañada
	Sotero Malabanán	N/A	Jhun Vitualla
	Christopher Dela Cruz	N/A	N/A
9:00 - 9:20 AM	[20] Automated Cycle Time and Process Bottleneck Analysis Through the Integration of AI Into Excel's Macro Programming	[16] Innovation and Inclusion of Pou Desiccant Dryer Technology to Eliminate Pad Discoloration Caused by Interaction of CDA Moisture to Metallic LGA Pads	[9] Defining the Die Attach Single Void Criteria on a Gallium Nitride (GaN) Rf Power Transistor in an Air Cavity Ceramic (ACC) Packaging
	P. IMES Corp.	STMicroelectronics, Inc.	Ampleon Philippines, Inc.
	Assembly	Quality	Failure Analysis and Reliability
	Angelica Esmeralda	Reinadd B. Abad	Olga Rivera
	Jermie De Mesa	Judioz M. Manejero	Aileen Perea
	N/A	Ivan B. Veridiano	Floralyn T. Custodio and Amir Mirzagheytaghi
9:20 - 9:40 AM	[4] Unlocking Insights from Multimodal Data: Advanced Data Analytics for Complex Data Sources and Processing	[6] Thermal Stability Assessment of Standard & Reduced Ni(Co)-Pd-Au Metalization Thickness on Cu-Mo70cu-Cu Heatspreaders Through Surface Characterization	[10] Optimizing Reliability Qualifications of Balanced Armatures: Use of Accelerated Test Conditions
	onsemi - Tarlac	Ampleon Philippines, Inc.	Knowles Electronics Philippines
	Support Systems	Product	Failure Analysis and Reliability
	Pamela Trizia S. Tarangco	Marty Lorgino D. Pulutan	Gle-Ann A. Sumalinog
	Harold Carlo P. Rebuldela	Jerlyn B. Bermudez	Andy Wences Q. Llerin
	Leonila J. Codog	Bongbong A. Mendoza	Dominic John P. Patarata
9:40 - 10:00 AM	[5] Data Analytics Through Automated Z-Score Diagnostic	[7] Wafer Reconstruction Process - A Breakthrough Technology Solutions Employed to Technical Diffuser Wafer Preparatory Manufacturing	[11] Finite Element Analysis on Wire Bond Break During TC and PTC: Evaluating Encapsulant Material Change as Potential Solution
	Knowles Electronics Philippines	STMicroelectronics, Inc.	Excelitas Technologies Philippines, Inc.
	Support Systems	Product	Failure Analysis and Reliability
	Ulysis J. Sebial	Jhanet R. Florendo	Jeanne Ranny B. De Guzman
	Raffy C. Cosep	Reinadd Jan Abad	Doods G. Decina
	Fredric Kristian Q. Besa	Judioz Manejero	Richard Raymond N. Dimagiba

10:00 - 10:20 AM	[3] Achieving Optimal Process Efficiency: Automated Solutions for Product Sampling and Tool State Change	[10] Reduction of IGBT Side Wall Crack	[1] Revolutionizing Maintenance Efficiency: ATE System Smart Tool
	<i>Texas Instruments Philippines, Inc. - Clark</i>	<i>onsemi - Tarlac</i>	<i>Texas Instruments Philippines, Inc. - Clark</i>
	<i>Assembly</i>	<i>Quality</i>	<i>Test</i>
	Louie Roy C. Esguerra	Jan Michael Castillo	Bonnierick J. Mendoza
	Marrion Russel L. Manarang	Joenilio Bautista	Jayber D. Semania
	Joshua Jerameel D. Serafica	N/A	N/A
10:20 - 10:40 AM	[5] Reduction of Kelvin Check Failure of device A at QFN Test	[6] Enhanced Automated Visual Inspection Management for Quality Control: Automatic Defect Classification (ADC)	[8] ATE System Power Supply Delta Automation: The Power of Predicting Tester Shutdowns
	<i>onsemi - Tarlac</i>	<i>Texas Instruments Philippines, Inc. - Clark</i>	<i>Texas Instruments Philippines, Inc. - Clark</i>
	<i>Quality</i>	<i>Quality</i>	<i>Test</i>
	Gimberlyne Joyce L. Barcarse	Mary Irene T. Reyes	Bonnierick J. Mendoza
	N/A	Derek Eric Biscocho	Jayber D. Semania
	N/A	N/A	N/A

LUNCH BREAK (12:00 PM AT THE FUNCTION ROOM 1)

12:45 PM - 2:00 PM (ANTS CLOSING & AWARDING CEREMONIES AT FUNCTION ROOM 1)